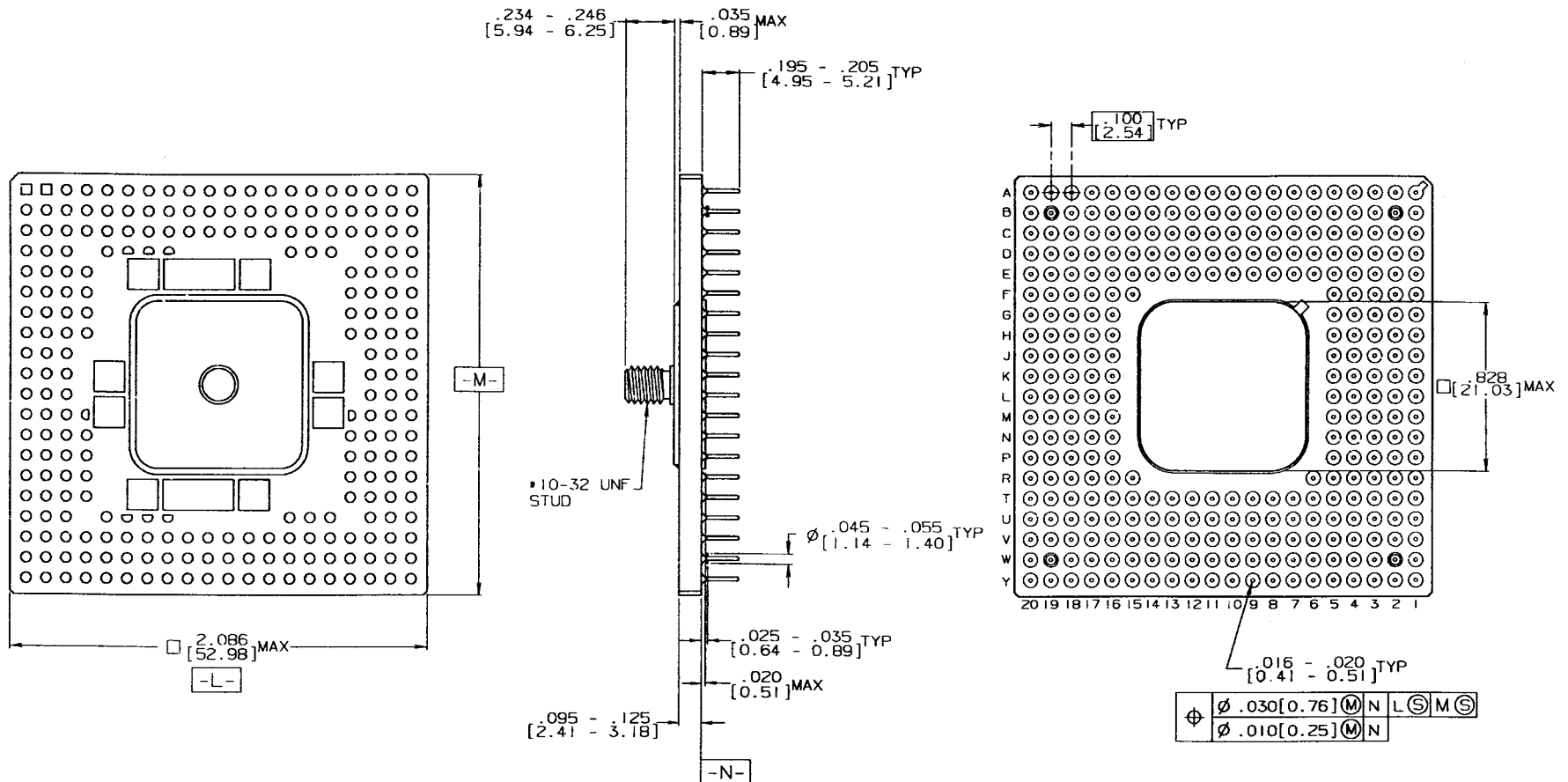


REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	07956	07/17/90 OCW/RC
B	CONVERT FROM HOLGUIN TO ANVILSK; ADD OPTION TABLE.	08511	04/04/91 PG/100



NOTES: UNLESS OTHERWISE SPECIFIED

- ALL EXPOSED METAL AND METALIZED SURFACES TO BE PLATED WITH 50 MICROINCHES/1.27 MICROMETERS MINIMUM GOLD OVER 50-350 MICROINCHES/1.27-8.89 MICROMETERS NICKEL.

OPTION	DESCRIPTION
02	WITHOUT STUD
01	WITH STUD

CONTROLLING DIMENSION: INCH			
APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION	
DRAWN O. WHITING	7/17/90	2900 Semiconductor Drive, Santa Clara, CA 95052-8090	
DESIGN D. J. J. J.	04/04/91	PIN GRID ARRAY, CERAMIC, 303 PIN, CAVITY DOWN	
ENGR / CHK. D. J. J.	4-8-91	SCALE	SIZE
APPROVAL		N/A	C
		DRAWING NUMBER	REV
		MKT-U303A	B
		DO NOT SCALE DRAWING	SHEET 1 OF 1